



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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LNJ03004BND1

Surface Mounting Chip LED

3230 Type

Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	430	mW
Forward current *1	I_F	120	mA
Pulse forward current *2	I_{FP}	200	mA
Junction temperature	T_j	110	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Lighting Color

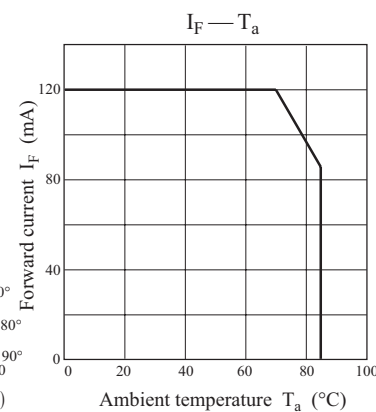
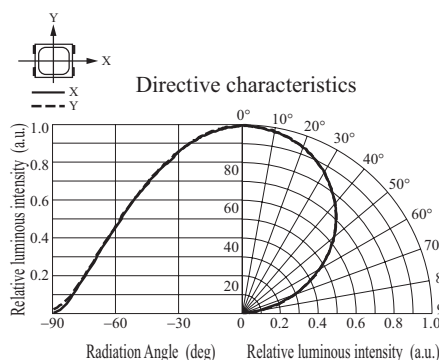
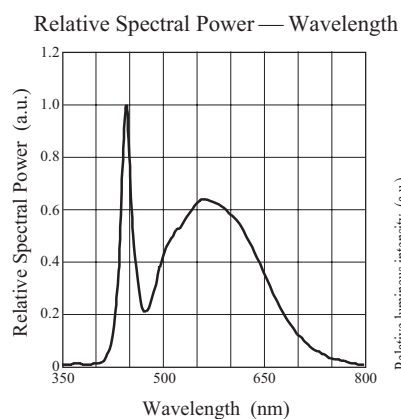
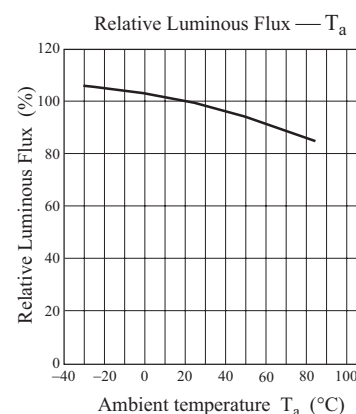
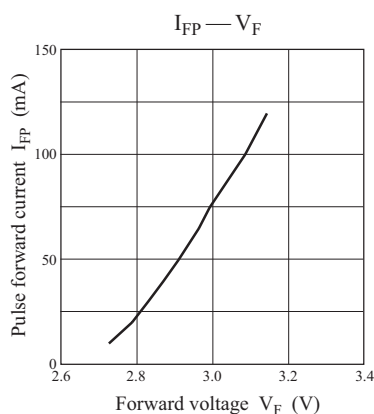
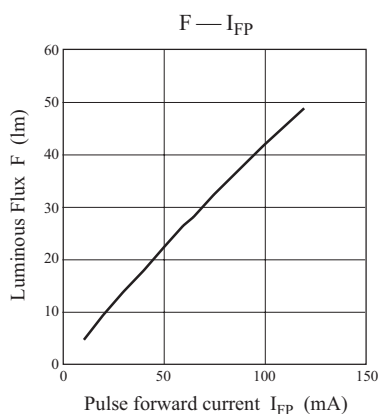
- White (5000 [Kelvin])

Note) *1: I_F is different by radiated factor of evaluation board.
This value is mounted on evaluation board at $R_{th-a} = 25.0^\circ\text{C/W}$.
*2: The condition of pulse current I_{FP} is 55 ms pulse width, 10 % duty.

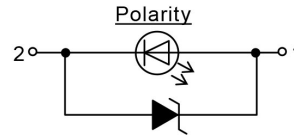
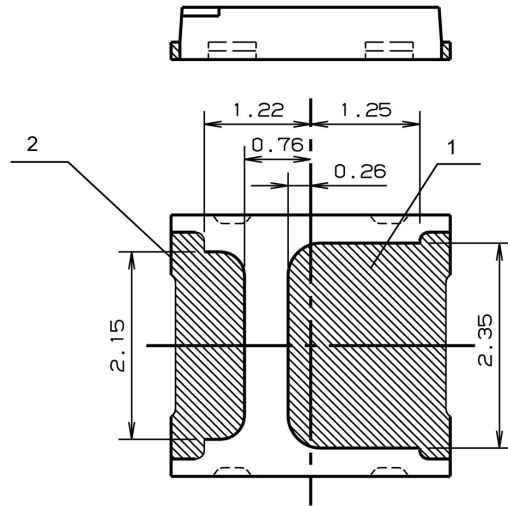
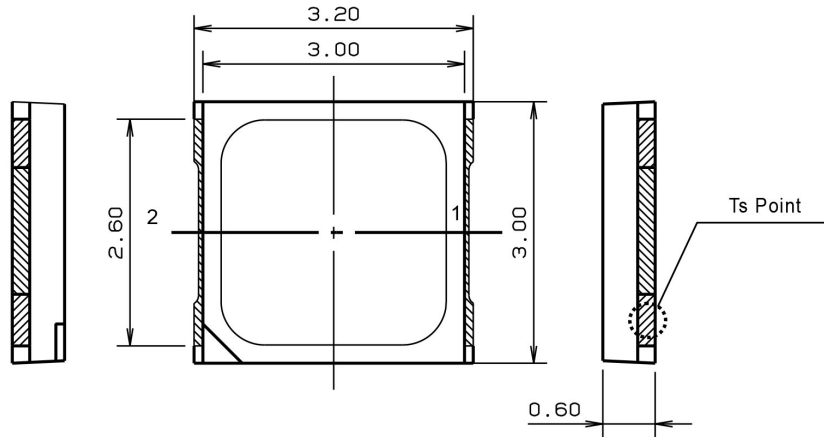
Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage *1	V_F	$I_{FP} = 60\text{ mA}$	2.7	2.95	3.2	V
Luminous flux *2	F	$I_{FP} = 60\text{ mA}$	22.0	26.5	30.0	lm
Chromaticity coordinates *3	x	$I_{FP} = 60\text{ mA}$		0.345		—
	y	$I_{FP} = 60\text{ mA}$		0.355		—
Color Rendering Index	Ra	$I_{FP} = 60\text{ mA}$		82		—

Note) *1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance $\pm 3\%$
*2: Complete Luminous flux measurement within 0.1 seconds. Tolerance $\pm 10\%$
*3: Complete Chromaticity coordinates measurement within 0.1 seconds. Tolerance of chromaticity is ± 0.01



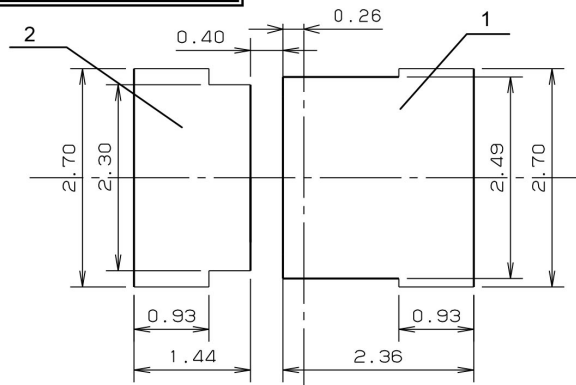
■ Package (Unit: mm)



1. Anode
2. Cathode

Item	Contents
Terminal Process	Cu + Ag Plate
Mold Material	Silicone Resin
Package Material	Polymer Base Reflection case

Reference Land Layout



(Note1) Tolerance unless otherwise specified : $\pm 0.2\text{mm}$

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